

What is claimed is:

1. A method for bonding an integrated circuit device to a glass substrate comprising:

- (a) providing a melting device;
- (b) melting a predetermined portion of the glass substrate by the melting device; and
- (c) bonding the integrated circuit device on the glass substrate.

2. The method as claimed in claim 1, wherein the melting device is a laser device.

3. The method as claimed in claim 1, wherein a protecting circuit, connecting with an external circuit, is disposed on the glass substrate, and the melting device comprises a first laser device for eliminating a predetermined portion of the protecting circuit and a second laser device for eliminating the predetermined portion of the glass substrate.

4. The method as claimed in claim 1, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is in contact with the predetermined portion, melted by the melting device, of the glass substrate when the integrated circuit device is bonded to the glass substrate.

5. The method as claimed in claim 4, wherein the connecting wire is bonded to the protecting circuit of the glass substrate via an adhesive and a plurality of conductive particles.

6. The method as claimed in claim 1, wherein the predetermined portion of the glass substrate is located at

edges of the glass substrate.

7. A method for bonding an integrated circuit device to a glass substrate comprising:

(a) bonding one portion of the integrated circuit device to a predetermined portion of the glass substrate so that a gap is formed between (the other portion) of the integrated circuit device and the glass substrate; and

(b) introducing resin into the gap so that the resin covers the predetermined portion of the glass substrate.

8. The method as claimed in claim 7, wherein the resin is cured by ultraviolet light.

9. The method as claimed in claim 7, wherein the predetermined portion of the glass substrate is located at edges of the glass substrate.

10. The method as claimed in claim 7, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is not in contact with the predetermined portion of the glass substrate due to the resin when the integrated circuit device is bonded to the glass substrate.

11. The method as claimed in claim 10, wherein a protecting circuit, connecting with an external circuit, is disposed on the glass substrate, and the connecting wire is bonded to the protecting circuit of the glass substrate via an adhesive and a plurality of conductive particles.